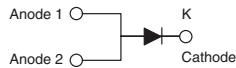
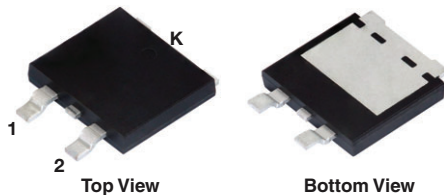


TMBS[®] (Trench MOS Barrier Schottky) Rectifier for PV Solar Cell Bypass Protection

 Ultra Low $V_F = 0.31\text{ V}$ at $I_F = 5\text{ A}$

eSMP[®] Series SMPD (TO-263AC)



LINKS TO ADDITIONAL RESOURCES


[3D Models](#)

PRIMARY CHARACTERISTICS

| | |
|--|-----------------|
| $I_{F(AV)}$ | 20 A |
| V_{RRM} | 45 V |
| I_{FSM} | 160 A |
| V_F at $I_F = 20\text{ A}$ ($T_A = 125\text{ °C}$) | 0.50 V |
| T_{OP} max. (AC model) | 150 °C |
| T_J max. (DC forward current) | 200 °C |
| Package | SMPD (TO-263AC) |
| Circuit configuration | Single |

MAXIMUM RATINGS ($T_A = 25\text{ °C}$ unless otherwise noted)

| PARAMETER | SYMBOL | V20DL45BP | UNIT |
|--|----------------------------|-------------|------|
| Maximum repetitive peak reverse voltage | V_{RRM} | 45 | V |
| Maximum DC forward current (fig. 1) | $I_{F(DC)}$ ⁽¹⁾ | 20 | A |
| Peak forward surge current 10 ms single half sine-wave superimposed on rated load | I_{FSM} | 160 | A |
| Operating junction temperature range (AC model) | T_{OP} | -40 to +150 | °C |
| Junction temperature in DC forward current without reverse bias, $t = \leq 1\text{ h}$ | T_J ⁽²⁾ | ≤ 200 | °C |

Note

⁽¹⁾ With heatsink

⁽²⁾ Meets the requirements of IEC 61215 ed.2 bypass diode thermal test

FEATURES

- Trench MOS Schottky technology
- Very low profile - typical height of 1.7 mm
- Ideal for automated placement
- Low forward voltage drop, low power losses
- High efficiency operation
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE

TYPICAL APPLICATIONS

For use in solar cell junction box as a bypass diode for protection, using DC forward current without reverse bias.

MECHANICAL DATA

Case: SMPD (TO-263AC)

Molding compound meets UL 94 V-0 flammability rating
Base P/N-M3 - halogen-free, RoHS-compliant, and commercial grade

Terminals: matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 suffix meets JESD 201 class 2 whisker test

Polarity: as marked

ELECTRICAL CHARACTERISTICS ($T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)

| PARAMETER | TEST CONDITIONS | SYMBOL | TYP. | MAX. | UNIT | |
|-------------------------------|---------------------|-----------------------------------|-------------|------|------|----|
| Instantaneous forward voltage | $I_F = 5\text{ A}$ | $T_A = 25\text{ }^\circ\text{C}$ | $V_F^{(1)}$ | 0.42 | - | V |
| | $I_F = 10\text{ A}$ | | | 0.48 | - | |
| | $I_F = 20\text{ A}$ | | | 0.55 | 0.64 | |
| | $I_F = 5\text{ A}$ | $T_A = 125\text{ }^\circ\text{C}$ | | 0.31 | - | |
| | $I_F = 10\text{ A}$ | 0.38 | | - | | |
| | $I_F = 20\text{ A}$ | 0.50 | | 0.58 | | |
| Reverse current | $V_R = 45\text{ V}$ | $T_A = 25\text{ }^\circ\text{C}$ | $I_R^{(2)}$ | - | 2.5 | mA |
| | | $T_A = 125\text{ }^\circ\text{C}$ | | 20 | 50 | |

Notes

- (1) Pulse test: 300 μs pulse width, 1 % duty cycle
 (2) Pulse test: Pulse width $\leq 5\text{ ms}$

THERMAL CHARACTERISTICS ($T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)

| PARAMETER | SYMBOL | V20DL45BP | UNIT |
|----------------------------|--------------------------|-----------|--------------------|
| Typical thermal resistance | $R_{\theta JC}$ | 1.6 | $^\circ\text{C/W}$ |
| | $R_{\theta JA}^{(1)(2)}$ | 45 | |

Notes

- (1) The heat generated must be less than the thermal conductivity from junction-to-ambient: $dP_D/dT_J < 1/R_{\theta JA}$
 (2) Free air, without heatsink

ORDERING INFORMATION (Example)

| PACKAGE | PREFERRED P/N | UNIT WEIGHT (g) | PACKAGE CODE | BASE QUANTITY | DELIVERY MODE |
|-----------------|----------------|-----------------|--------------|---------------|------------------------------------|
| SMPD (TO-263AC) | V20DL45BP-M3/I | 0.55 | I | 2000/reel | 13" diameter plastic tape and reel |

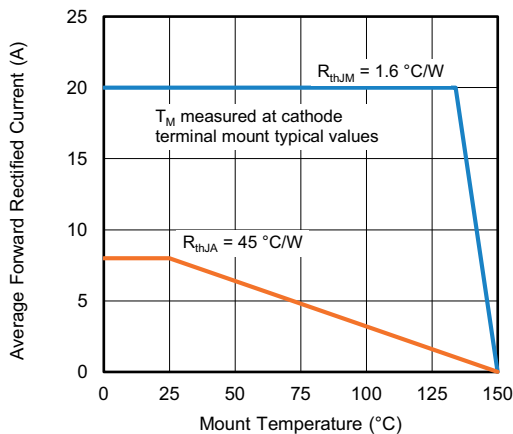
RATINGS AND CHARACTERISTICS CURVES ($T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)


Fig. 1 - Forward Current Derating Curve

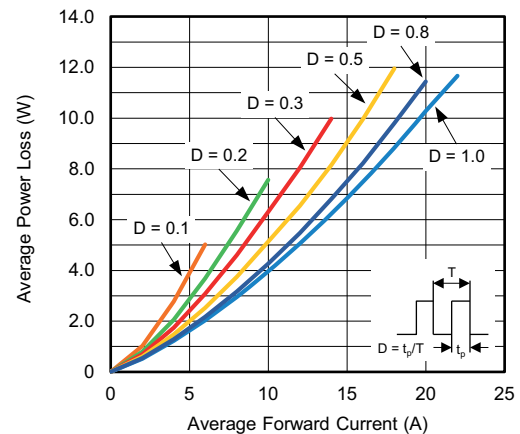


Fig. 2 - Forward Power Loss Characteristics

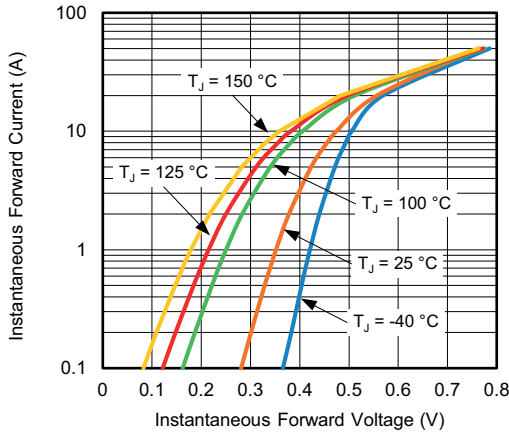


Fig. 3 - Typical Instantaneous Forward Characteristics

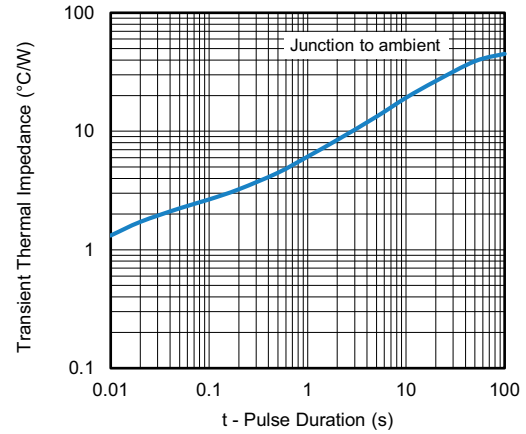


Fig. 6 - Typical Transient Thermal Impedance

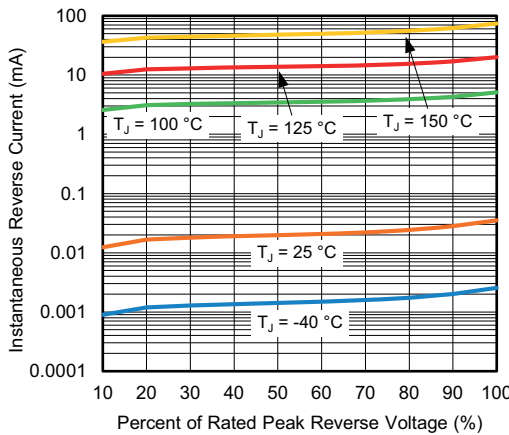


Fig. 4 - Typical Reverse Characteristics

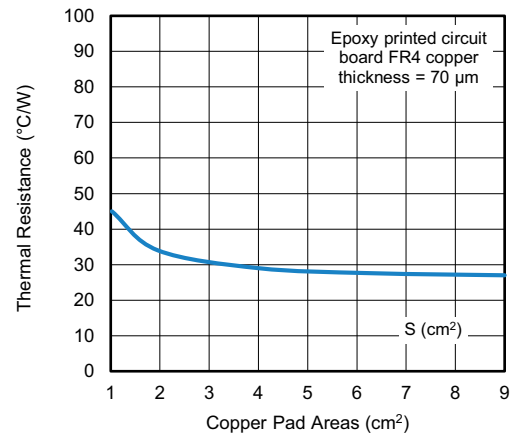


Fig. 7 - Thermal Resistance Junction-to-Ambient vs. Copper Pad Areas

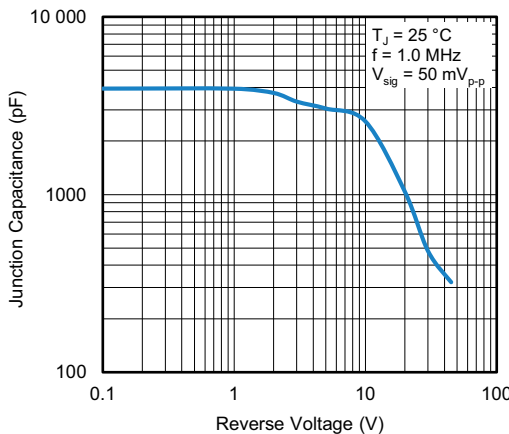
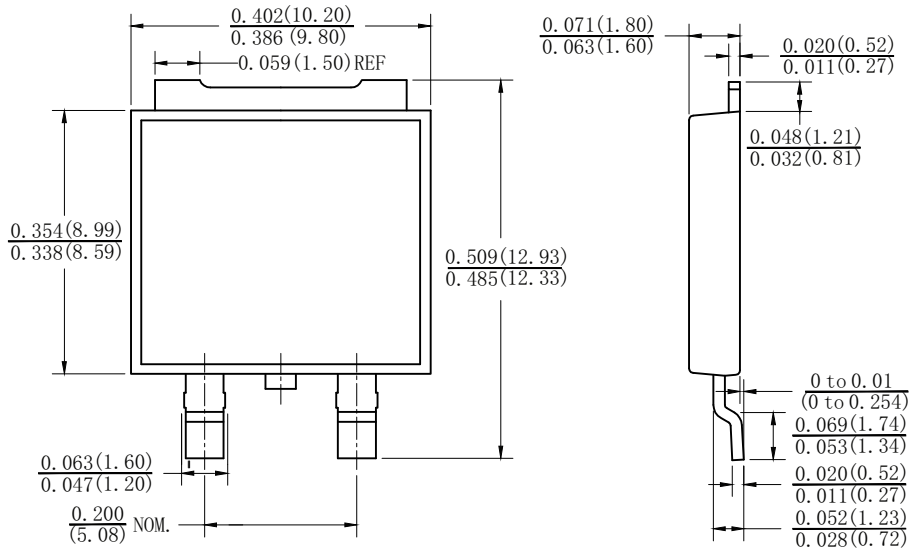


Fig. 5 - Typical Junction Capacitance

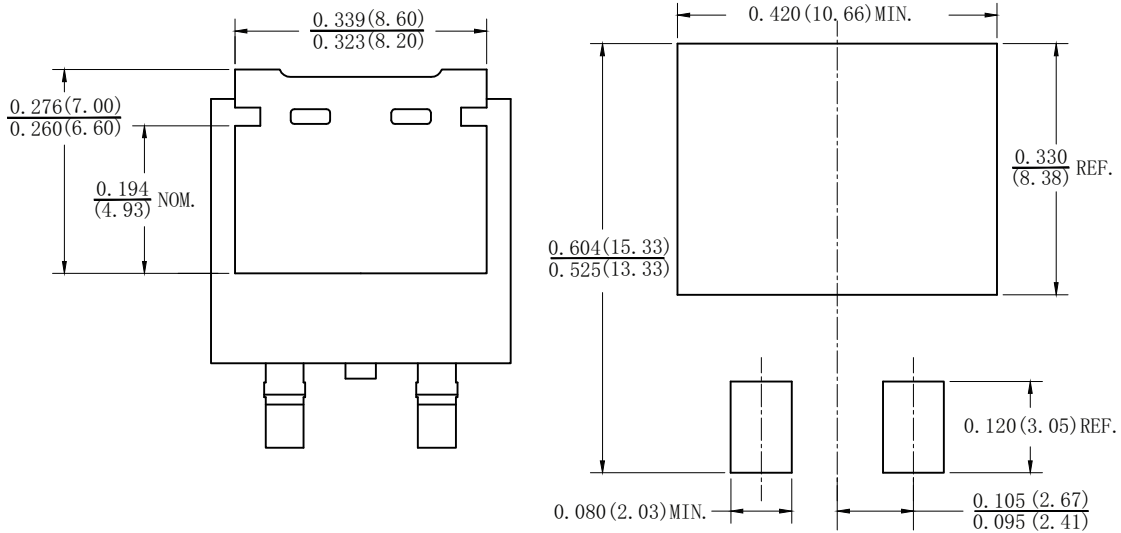


PACKAGE OUTLINE DIMENSIONS in inches (millimeters)

SMPD (TO-263AC)



Mounting Pad Layout





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